



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A0904-03

PCN Type: Manufacturing Site - Alternate Assembly Location
Data Sheet Change: None
 No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines as an alternate assembly facility for 19mm x 19mm FCBGA-324, RoHS version. There is no change to the moisture performance of this package using the assembly material sets as listed in the below table.

Qualification Information and Qualification Data:

Affected Packages: 19mm x 19mm FCBGA-324 (AR324)

Assembly Material: See Table below

Description	Existing	Add
Assembly Location	SPIL, Taiwan	Amkor, Philippines
Assembly Materials	Heat spreader thermo grease: Shinetsu X23-7772-4_2	DCL-5
	Adhesive: Ablestik I/AMC723_1.5	DCL-5
	Die bump: 95Pb5Sn	95Pb5Sn
	Underfill: Namics U8439-1	NAU8
	Substrate: E679FGBR/ABF-GX3/AUS703	E679FGBR/ABF-GX3/AUS703
	Solder Balls: Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5



Integrated Device Technology, Inc.
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Qualification Test Plans and Results :

IDT Qual Plan#: P08-11-05
Qual Vehicle: 19mm x 19mm FCBGA-324, 2 lots

Test Description	Test Method (Latest specs in effect)	Test Results (SS/Rej)	
		Lot 1	Lot 2
* Temperature Cycling (-55°C to +125°C, 1000 cycles)	JESD22-A104	45/0	45/0
* Unbiased HAST (130°C, 85% RH, 100 Hrs)	JESD22-A118	45/0	45/0
High Temp. Storage (150 °C, 1000 Hrs)	JESD22-A103	77/0	77/0

Note: * Test require moisture pre-conditioning sequence per JESD22-A113.



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Affected Part Number

Part Number	Part Number	Part Number	Part Number
80KSW0001AR	80KSW0002AR	80KSW0003AR	80KSW0004AR
80KSW0001ARI	80KSW0002ARI	80KSW0003ARI	80KSW0004ARI